- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

	AVERAGE PROPAGATION	TYPICAL
	DELAY FROM	POWER
	DATA INPUT	DISSIPATIONT
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

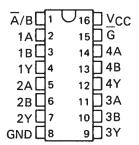
[†]Off state (worst case)

description

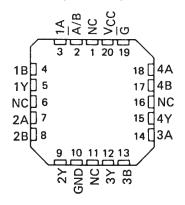
These devices are designed to multiplex signals from four-bit data sources to four-output data lines in busorganized systems. The 3-state outputs will not load the data lines when the output control pin (\overline{G}) is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of -55° C to 125°C; Series 74LS and 74S are characterized for operation from 0°C to 70°C.

SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . J OR W PACKAGE SN74LS257B, SN74S257, SN74LS258B, SN74S258 . . . D OR N PACKAGE (TOP VIEW)



SN54LS257B, SN54S257, SN54LS258B, SN54S258 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection.

FUNCTION TABLE

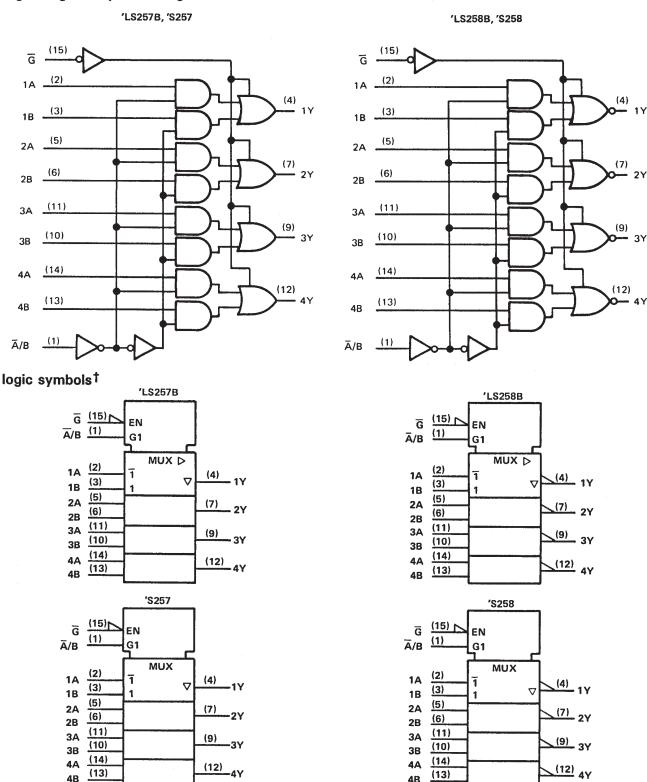
	INPUTS			OUTPUT Y			
OUTPUT CONTROL	SELECT	А	В	'LS257B 'S257	'LS258B 'S258		
Н	Х	Х	Х	Z	Z		
L	L,	L	Х	L	Н		
L	L	Н	Х	Н	L		
L	Н	Х	L,	L	Н		
L	Н	Х	Н	Н	L		

H = high level, L = low level, X = irrelevant,

Z = high Impedance (off)



logic diagrams (positive logic)



[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

(12)

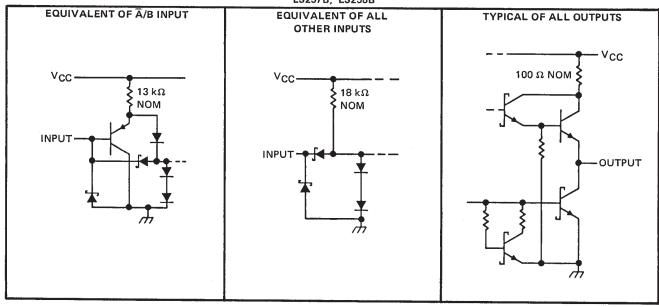
(13)4B



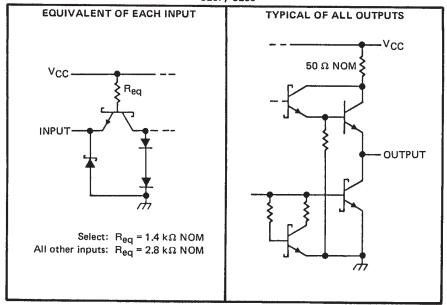
(13)

schematics of inputs and outputs

'LS257B, 'LS258B



'S257, 'S258



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: 'LS257B, 'LS258B Circuits	
'S257, 'S258 Circuits	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS', SN54S' Circuits	55°C to 125°C
	0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.



SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SDLS148 - OCTOBER 1976 - REVISED MARCH 1988

recommended operating conditions

		SN54LS'			SN74LS'			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH High-level input voltage	2			2			V	
VIL Low-level input voltage			0.7			0.8	V	
IOH High-level output current		··	– 1			- 2.6	mA	
IOL Low-level output current			12			24	mA	
TA Operating free-air temperature	55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

i ,	PARAMETER	TE	ST CONDITION	ust		SN54LS	3'				
		• •	ST CONDITION	40.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN,	1 ₁ = 18 mA				- 1.5			1.5	V
VOH		V _{CC} = MIN, I _{OH} = MAX	$V_{IH} = 2 V$,	VIL = MAX,	2.4	3.4		2.4	3.1		٧
VOL		V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
- OL		VIL = MAX,		I _{OL} = 24 mA					0.35	0.5	V
lozh_		V _{CC} = MAX,	V _{IH} = 2 V,	V _O = 2.7 V			20			20	μΑ
lozL		V _{CC} - MAX,	$V_{1H} = 2 V$	V _O = 0.4 V			20			- 20	μΑ
11		V _{CC} = MAX,	V1 = 7 V				0.1			0.1	mA
1H		V _{CC} = MAX,	V1 = 2.7 V				20			20	μΑ
ll L		V _{CC} = MAX,	V _I = 0.4 V				- 0.4			- 0.4	mA
los §		V _{CC} = MAX,			- 30		- 130	30		- 130	mA
	All outputs high					8	12	1	8	12	
	All outputs low			'LS257B		12	18		12	18	1
laa	All outputs off	V	011 0			13	19		13	19]
lcc	All outputs high	V _{CC} = MAX,	See Note 2			6	9		6	9	mA
	All outputs low			'LS258B		10	15		10	15	1
	All outputs off					11	16		11	16	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, VCC = 5 V, $T_A = 25^{\circ}$ C, $R_L = 667 \Omega$

PARAMETER	FROM	то	TEST CONDITIONS			'LS257	В		'LS258	В				
TAIN METER	(INPUT)	(OUTPUT)	1231 001	IDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	דומט			
^t PLH	Data	Any			8	13		7	12					
^t PHL	Data	Ally				10	15		11	17	ns			
^t PLH	Select	Anv	C _L = 45 pF,	See Note 3		16	21		14	21				
^t PHL		Any	Any			C[- 45 μ-,	See Note S		17	24		19	24	ns
^t PZH	Output								15	30		15	30	
^t PZL	Control	Ally				19	30		20	30	ns			
^t PHZ	Output	Any	C. = = = =	Con Note 2		18	30		18	30				
^t PLZ	Control	"	$C_L = 5 pF$,	See Note 3		16	25		16	25	ns			

[¶]tpLH = propagation delay time, low-to-high-level output

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level



[§]Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		SN54S'			UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	CIVIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-2			6.5	mΑ
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							'S257		'S258			UNIT
	PARAME'	TER	TEST	CONDITIONS		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNII
VIH	High-level input	voltage				2			2			٧
VIL	Low-level input				1			0.8			0.8	٧
VIK	Input clamp vol		V _{CC} = MIN,	I _I = -18 mA				1.2			-1.2	٧
		V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -1 mA	SN74S'	2.7			2.7			V	
VOH	OH High-level output voltage		V _{CC} = MIN,		SN54S'	2.4	3.4		2.4	3.4		ľ
			$V_{IL} = 0.8 V$	IOH = MAX	SN74S'	2.4	3.2		2.4	3.2		
VOL	Low-level outpu	ut voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{1H} = 2 V, I _{OL} = 20 mA				0.5			0.5	٧
IOZH	Off-state output	· ·	V _{CC} = MAX, V _O = 2.4 V	V _{IH} = 2 V,				50			50	μΑ
IOZL	Off-state output	•	V _{CC} = MAX, V _O = 0.5 V	V _{IH} = 2 V,				-50			-50	μА
l _l	Input current a	t maximum	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
	High-level	Sinput		0.7.1				100			100	μΑ
ΉН	input current	Any other	V _{CC} = MAX,	V ₁ = 2.7 V				50			50] "
	Low-level	S input						-4			-4	mA
HL	input current	Any other	V _{CC} = MAX	V = 0.5 V				-2			-2	1111/4
los	Short-circuit ou	itput current §	V _{CC} = MAX			-40		-100	-40		-100	mA
		All outputs high					44	68		36	56	1
ICC	Supply current	All outputs low	VCC = MAX,	See Note 2			60	93		52	81	mA
		All outputs off]				64	99		56	87	<u> </u>

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ}\text{C}$.

NOTE 2: ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, VCC = 5 V, $TA = 25^{\circ}\text{C}$, $RL = 280 \Omega$

	FROM	то	TEST		'S257			'S258		UNIT
PARAMETER¶	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
tPLH	5-1-	A ===			5	7.5		4	6	ns
tPHL	Data	Any			4.5	6.5		4	6] '''
tPLH			$C_L = 15 pF$,		8.5	15		8	12	ns
tPHL	Select	Any	See Note 3		8.5	15		7.5	12	113
tPZH	Output	_	1		13	19.5		13	19.5	ns
tPZL	Control	Any			14	21		14	21	1 "
tPHZ	Output	1	$C_L = 5 pF$,		5.5	8.5		5.5	8.5	
tPLZ	Control	Any	See Note 3		9	14		9	14	ns

¶f_{max} = Maximum clock frequency

tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

tpZH = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

 $t_{PZL} \equiv$ output enable time to low level $t_{PHZ} \equiv$ output disable time from high level

tpLZ ≡ output disable time from low level



Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
7603701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701EA SNJ54LS257BJ	Samples
7603701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Samples
7603701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Samples
7603801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Samples
7603801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Samples
8002301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Samples
8002301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Samples
8002301FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Samples
8002301FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Samples
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
JM38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
JM38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
JM38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
JM38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
M38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
M38510/07906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BEA	Samples
M38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
M38510/07906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07906BFA	Samples
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906B2A	Samples
M38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
M38510/30906BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BEA	Samples
M38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
M38510/30906BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30906BFA	Samples
SN54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS257BJ	Samples
SN54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS257BJ	Samples
SN54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS258BJ	Samples
SN54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS258BJ	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S257J	Samples
SN54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S257J	Samples
SN74LS257BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS257B	Samples
SN74LS257BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS257BN	Samples
SN74LS257BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS257BN	Samples
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS257B	Samples
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS257B	Samples
SN74LS258BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS258B	Samples
SN74LS258BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS258BN	Samples
SN74LS258BN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS258BN	Samples
SN74S257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S257N	Samples
SN74S257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S257N	Samples
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 257BFK	Samples
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 257BFK	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material ⁽⁶⁾	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701EA SNJ54LS257BJ	Samples
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701EA SNJ54LS257BJ	Samples
SNJ54LS257BW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Samples
SNJ54LS257BW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603701FA SNJ54LS257BW	Samples
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Samples
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603801EA SNJ54LS258BJ	Samples
SNJ54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S257J	Samples
SNJ54S257J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S257J	Samples
SNJ54S257W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S257W	Samples
SNJ54S257W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S257W	Samples
SNJ54S258J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Samples
SNJ54S258J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301EA SNJ54S258J	Samples
SNJ54S258W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Samples
SNJ54S258W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002301FA SNJ54S258W	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS257B, SN54LS258B, SN54S257, SN74LS257B, SN74LS258B, SN74S257:

Catalog: SN74LS257B, SN74LS258B, SN74S257

Military: SN54LS257B, SN54LS258B, SN54S257

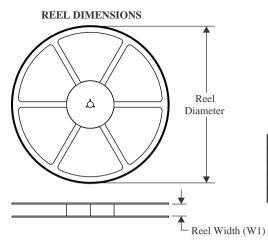
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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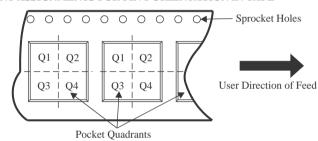
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS257BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS257BNSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS258BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device Package Type		Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74LS257BDR	SOIC	D	16	2500	340.5	336.1	32.0	
SN74LS257BNSR	SO	NS	16	2000	356.0	356.0	35.0	
SN74LS258BDR	SOIC	D	16	2500	340.5	336.1	32.0	



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
7603701FA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/07906BFA W		CFP	16	1	506.98	26.16	6220	NA
JM38510/30906B2A	JM38510/30906B2A FK		20	1	506.98	12.06	2030	NA
JM38510/30906BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/07906BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/30906B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30906BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS257BD	D	SOIC	16	40	507	8	3940	4.32
SN74LS257BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS257BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS258BD	D	SOIC	16	40	507	8	3940	4.32
SN74LS258BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS258BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74S257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74S257N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS257BFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS257BW	W	CFP	16	1	506.98	26.16	6220	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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